

PTO-1449	Application No. unknown	Applicant(s) Scott R. Runnels	
	Docket Number 090936.0395	Group Art Unit unknown 2125	Filing Date October 24, 2000

**Information Disclosure Citation
in an Application**

U.S. PATENT DOCUMENTS

		DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
QUP	A	5,655,110	08/05/97	Krivokapic et al.	395	500	
QUP	B	5,665,202	09/09/97	Subramanian et al.	438	692	
QUP	C	5,637,031	06/10/97	Chen	541	41	
QUP	D	5,599,423	02/04/97	Parker et al.	156	636.1	
QUP	E	5,526,293	06/11/96	Mozumder et al.	364	578	
QUP	F	5,514,245	05/07/96	Doan et al.	156	636.1	
QUP	G	5,471,403	11/28/95	Fujimaga	364	488	
QUP	H	5,367,465	11/22/94	Tazawa et al.	364	468	
QUP	I	4,833,617	05/23/89	Wang	364	474.15	
	J						

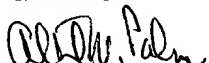
FOREIGN PATENT DOCUMENTS

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	K							

NON-PATENT DOCUMENTS

		DOCUMENT (Including Author, Title, Source, and Pertinent Pages)					DATE
QUP	L	M. Bhusan et al., "Chemical-Mechanical Polishing in Semidirect Contact Mode", J. Electrochem. Soc., Vol. 142, No. 11, pp. 3845-3851					11/95
QUP	M	R. Jairath et al., "Role of Consumables in the Chemical Mechanical Polishing (CMP) of Silicon Oxide Films", SEMATECH Paper					
QUP	N	P. Rentein et al., "Characterization of Mechanical Planarization Processes", VMIC Conference, pp. 57-63					06/90
QUP	O	J. Warnock, "A Two Dimensional Process Model for Chemimechanical Polish Planarization", J. Electrochem. Soc., Vol. 138, No. 8, pp. 2398-2402					08/91
QUP	P	S. Sivaram et al., "Measurement and Modeling of Pattern Sensitivity During Chemical Mechanical Polishing of Interleaved Dielectrics", SEMATECH Paper, Conference Proceedings ULSI-VII, Materials Research Society, pp. 511-517					1992
QUP	Q	S. Runnels, "Advances in Physically Based Erosion Simulators for CMP", J. of Electronic Materials, Vol. 25, No. 10, pp. 1574-1580					1996
QUP	R	M. Ruttan et al., "Pattern Density Effects in Tungsten CMP", Semiconductor International, pp. 123-129					09/95
QUP	S	R. Jairath et al., "Consumables for the Chemical Mechanical Polishing (CMP) of Dielectrics and Conductors", Mat. Res. Soc., Invited Paper					Spring 1994
QUP	T	R. Sivaram et al., "Chemical Mechanical Polishing of Interleaved Dielectrics: Models for Removal Rate and Planarity", Mat. Res. Soc. Smp. Proc. Vol. 260, pp. 53-64					1992
QUP	U	M. Desai et al., "Chemical Mechanical Polishing for Planarization in Manufacturing Environment", Mat. Res. Soc. Symp. Proc. Vol. 337, pp. 99-104					1994

EXAMINER



ALBERT W. PALADINO
PATENT EXAMINER

DATE CONSIDERED

1/6/04

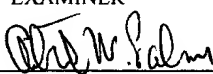
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	A						
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	D						
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FOREIGN PATENT DOCUMENTS							
		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
	G						

NON-PATENT DOCUMENTS			
		DOCUMENT (Including Author, Title, Source, and Pertinent Pages)	DATE
<input checked="" type="checkbox"/>	H	A. Hu et al., "Concurrent Deployment of Run by Run Controller Using SCC Framework", IEEE/SEMI Int'l Semiconductor Manufacturing Science Symp. pp. 126-132	1993
<input checked="" type="checkbox"/>	I	B. Stine et al., "A Closed-Form Analytic Model for ILD Thickness Variation in CMP Processes, CMP-MIC Conference, pp. 266-272	1997
<input checked="" type="checkbox"/>	J	V. H. Bulsara et al., "Mechanics of Polishing", Transactions of the ASME, Vol. 65, pp. 410-416	06/98
<input checked="" type="checkbox"/>	K	O.G. Chekina et al., "Wear-Contact Problems and Modeling of Chemical Mechanical Polishing", J. Electrochem. Soc., Vol 145, No. 6, pp. 2100-2106	06/98
<input checked="" type="checkbox"/>	L	H. Kim et al., "The Effect of the Pattern Sensitivity on Interlayer Dielectric Planarization", CMP-MIC Conference, pp. 103-109	1998
<input checked="" type="checkbox"/>	M	W.-T. Tseng et al., "Distribution of Pressure and Its Effects on the Removal Rate During Chemical-Mechanical Polishing Process", CMP-MIC Conference, pp. 87-94	1998
<input checked="" type="checkbox"/>	N	J. Grillaert et al., "Modeling Step Height reduction and Local Removal Rates Based on Pad-Substrate Interactions", CMP-MIC Conference, pp. 79-86	1998
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EXAMINER  ALBERT W. PALADINI PATENT EXAMINER	DATE CONSIDERED 1/6/04
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